

ABSTRACT

The present invention is a method and apparatus for a very low profile ball grid array package. A substrate is provided with an aperture. A thin sheet material is secured to the substrate, covering the aperture, so as to form a cavity. A semiconductor die is mounted in the formed cavity on the thin sheet material. The semiconductor die is encapsulated with the thin sheet material supporting it during encapsulation. The use of the thin sheet material to form the cavity is a cost effective way to construct a ball grid array package having a very low profile.